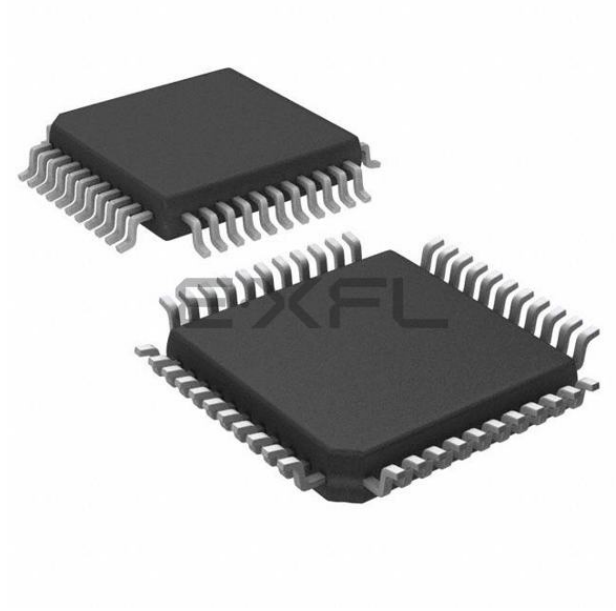

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-MQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c44-16-pq

2.0 PIC17C4X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC17C4X Product Selection System section at the end of this data sheet. When placing orders, please use the "PIC17C4X Product Identification System" at the back of this data sheet to specify the correct part number.

For the PIC17C4X family of devices, there are four device "types" as indicated in the device number:

1. **C**, as in PIC17**C**42. These devices have EPROM type memory and operate over the standard voltage range.
2. **LC**, as in PIC17**LC**42. These devices have EPROM type memory, operate over an extended voltage range, and reduced frequency range.
3. **CR**, as in PIC17**CR**42. These devices have ROM type memory and operate over the standard voltage range.
4. **LCR**, as in PIC17**LCR**42. These devices have ROM type memory, operate over an extended voltage range, and reduced frequency range.

2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package, is optimal for prototype development and pilot programs.

The UV erasable version can be erased and reprogrammed to any of the configuration modes. Microchip's PRO MATE™ programmer supports programming of the PIC17C4X. Third party programmers also are available; refer to the *Third Party Guide* for a list of sources.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers expecting frequent code changes and updates.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must also be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your local Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround Production (SQTP^{SM}) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password or ID number.

ROM devices do not allow serialization information in the program memory space.

For information on submitting ROM code, please contact your regional sales office.

2.5 Read Only Memory (ROM) Devices

Microchip offers masked ROM versions of several of the highest volume parts, thus giving customers a low cost option for high volume, mature products.

For information on submitting ROM code, please contact your regional sales office.

5.0 INTERRUPTS

The PIC17C4X devices have 11 sources of interrupt:

- External interrupt from the RA0/INT pin
- Change on RB7:RB0 pins
- TMR0 Overflow
- TMR1 Overflow
- TMR2 Overflow
- TMR3 Overflow
- USART Transmit buffer empty
- USART Receive buffer full
- Capture1
- Capture2
- T0CKI edge occurred

There are four registers used in the control and status of interrupts. These are:

- CPUSTA
- INTSTA
- PIE
- PIR

The CPUSTA register contains the GLINTD bit. This is the Global Interrupt Disable bit. When this bit is set, all interrupts are disabled. This bit is part of the controller core functionality and is described in the Memory Organization section.

When an interrupt is responded to, the GLINTD bit is automatically set to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with the interrupt vector address. There are four interrupt vectors. Each vector address is for a specific interrupt source (except the peripheral interrupts which have the same vector address). These sources are:

- External interrupt from the RA0/INT pin
- TMR0 Overflow
- T0CKI edge occurred
- Any peripheral interrupt

When program execution vectors to one of these interrupt vector addresses (except for the peripheral interrupt address), the interrupt flag bit is automatically cleared. Vectoring to the peripheral interrupt vector address does not automatically clear the source of the interrupt. In the peripheral interrupt service routine, the source(s) of the interrupt can be determined by testing the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid infinite interrupt requests.

All of the individual interrupt flag bits will be set regardless of the status of their corresponding mask bit or the GLINTD bit.

For external interrupt events, there will be an interrupt latency. For two cycle instructions, the latency could be one instruction cycle longer.

The “return from interrupt” instruction, `RETFIE`, can be used to mark the end of the interrupt service routine. When this instruction is executed, the stack is “POPed”, and the GLINTD bit is cleared (to re-enable interrupts).

FIGURE 5-1: INTERRUPT LOGIC

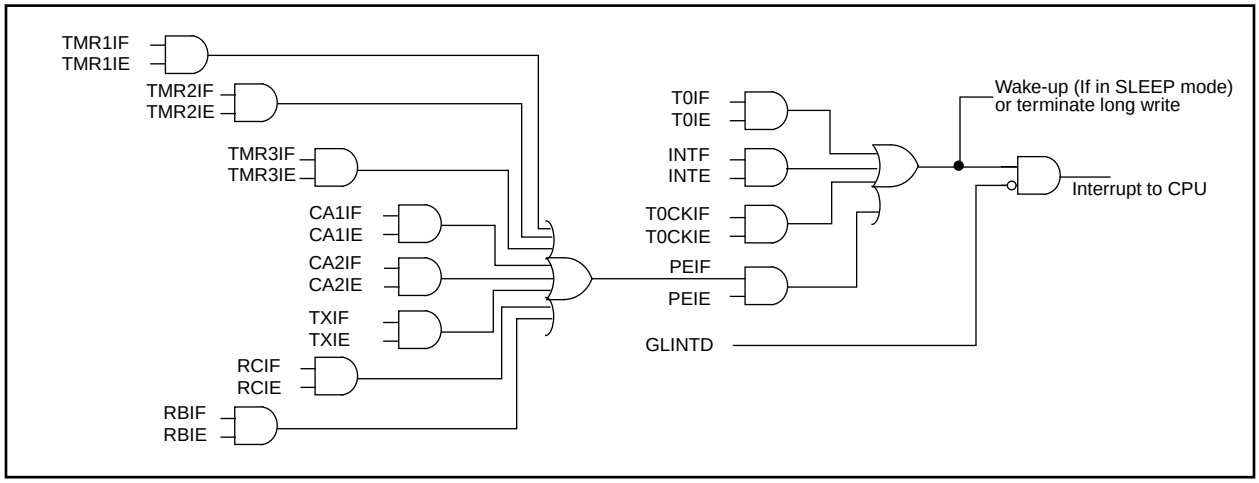


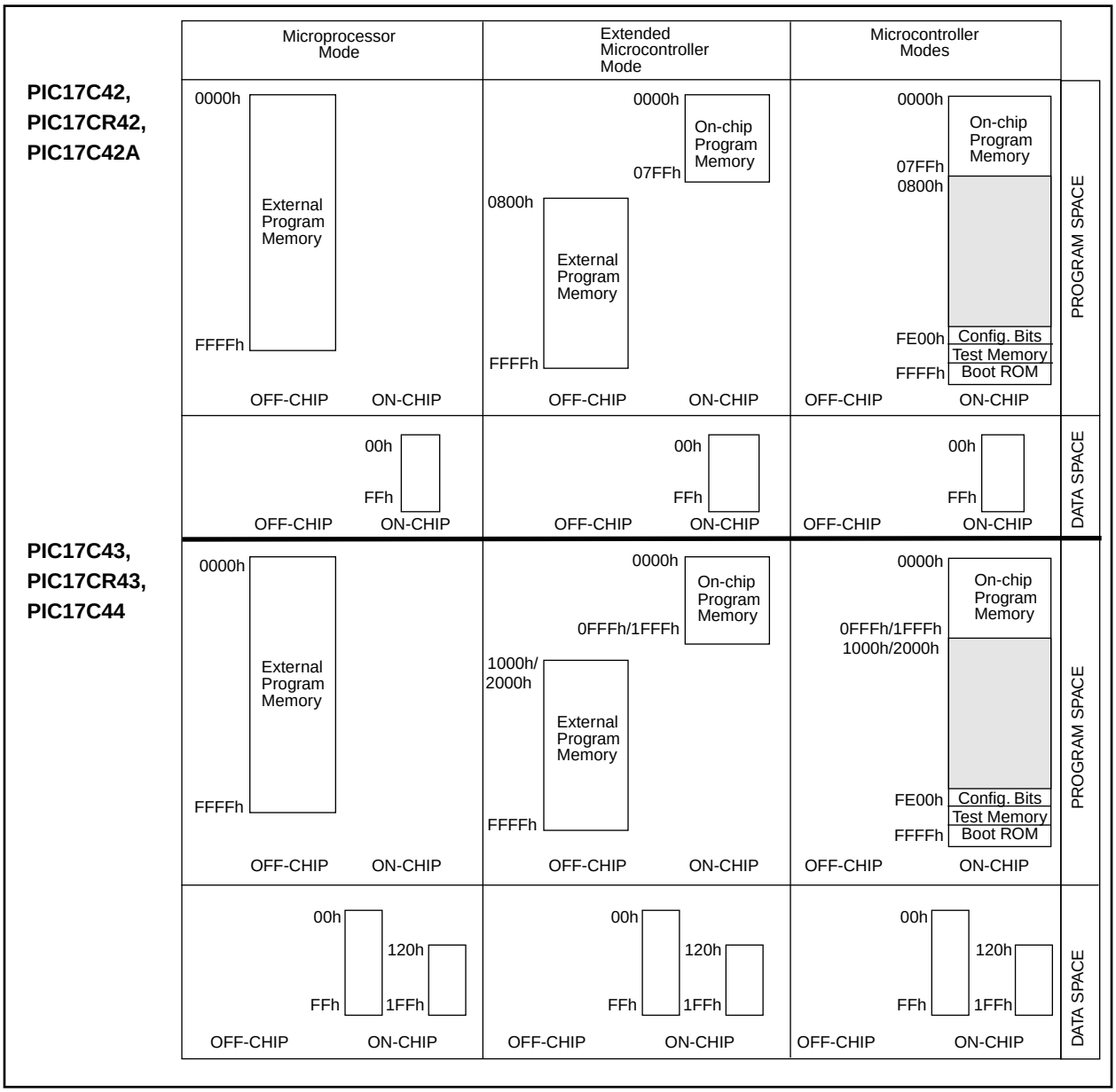
TABLE 6-1: MODE MEMORY ACCESS

Operating Mode	Internal Program Memory	Configuration Bits, Test Memory, Boot ROM
Microprocessor	No Access	No Access
Microcontroller	Access	Access
Extended Microcontroller	Access	No Access
Protected Microcontroller	Access	Access

The PIC17C4X can operate in modes where the program memory is off-chip. They are the microprocessor and extended microcontroller modes. The microprocessor mode is the default for an unprogrammed device.

Regardless of the processor mode, data memory is always on-chip.

FIGURE 6-2: MEMORY MAP IN DIFFERENT MODES



8.0 HARDWARE MULTIPLIER

All PIC17C4X devices except the PIC17C42, have an 8 x 8 hardware multiplier included in the ALU of the device. By making the multiply a hardware operation, it completes in a single instruction cycle. This is an unsigned multiply that gives a 16-bit result. The result is stored into the 16-bit PRODuct register (PRODH:PRODL). The multiplier does not affect any flags in the ALUSTA register.

Making the 8 x 8 multiplier execute in a single cycle gives the following advantages:

- Higher computational throughput
- Reduces code size requirements for multiply algorithms

The performance increase allows the device to be used in applications previously reserved for Digital Signal Processors.

Table 8-1 shows a performance comparison between the PIC17C42 and all other PIC17CXX devices, which have the single cycle hardware multiply.

Example 8-1 shows the sequence to do an 8 x 8 unsigned multiply. Only one instruction is required when one argument of the multiply is already loaded in the WREG register.

Example 8-2 shows the sequence to do an 8 x 8 signed multiply. To account for the sign bits of the arguments, each argument's most significant bit (MSb) is tested and the appropriate subtractions are done.

EXAMPLE 8-1: 8 x 8 MULTIPLY ROUTINE

```
MOVFP    ARG1, WREG
MULWF    ARG2          ; ARG1 * ARG2 ->
                       ;   PRODH:PRODL
```

EXAMPLE 8-2: 8 x 8 SIGNED MULTIPLY ROUTINE

```
MOVFP    ARG1, WREG
MULWF    ARG2          ; ARG1 * ARG2 ->
                       ;   PRODH:PRODL
BTFSC    ARG2, SB      ; Test Sign Bit
SUBWF    PRODH, F      ; PRODH = PRODH
                       ;         - ARG1
MOVFP    ARG2, WREG
BTFSC    ARG1, SB      ; Test Sign Bit
SUBWF    PRODH, F      ; PRODH = PRODH
                       ;         - ARG2
```

TABLE 8-1: PERFORMANCE COMPARISON

Routine	Device	Program Memory (Words)	Cycles (Max)	Time	
				@ 25 MHz	@ 33 MHz
8 x 8 unsigned	PIC17C42	13	69	11.04 µs	N/A
	All other PIC17CXX devices	1	1	160 ns	121 ns
8 x 8 signed	PIC17C42	—	—	—	N/A
	All other PIC17CXX devices	6	6	960 ns	727 ns
16 x 16 unsigned	PIC17C42	21	242	38.72 µs	N/A
	All other PIC17CXX devices	24	24	3.84 µs	2.91 µs
16 x 16 signed	PIC17C42	52	254	40.64 µs	N/A
	All other PIC17CXX devices	36	36	5.76 µs	4.36 µs

FIGURE 12-2: TCON2 REGISTER (ADDRESS: 17h, BANK 3)

R - 0	R - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0
CA2OVF	CA1OVF	PWM2ON	PWM1ON	CA1/$\overline{PR3}$	TMR3ON	TMR2ON	TMR1ON
bit7							bit0

R = Readable bit
W = Writable bit
-n = Value at POR reset

bit 7: **CA2OVF**: Capture2 Overflow Status bit
This bit indicates that the capture value had not been read from the capture register pair (CA2H:CA2L) before the next capture event occurred. The capture register retains the oldest unread capture value (last capture before overflow). Subsequent capture events will not update the capture register with the Timer3 value until the capture register has been read (both bytes).
1 = Overflow occurred on Capture2 register
0 = No overflow occurred on Capture2 register

bit 6: **CA1OVF**: Capture1 Overflow Status bit
This bit indicates that the capture value had not been read from the capture register pair (PR3H/CA2H:PR3L/CA2L) before the next capture event occurred. The capture register retains the oldest unread capture value (last capture before overflow). Subsequent capture events will not update the capture register with the TMR3 value until the capture register has been read (both bytes).
1 = Overflow occurred on Capture1 register
0 = No overflow occurred on Capture1 register

bit 5: **PWM2ON**: PWM2 On bit
1 = PWM2 is enabled (The RB3/PWM2 pin ignores the state of the DDRB<3> bit)
0 = PWM2 is disabled (The RB3/PWM2 pin uses the state of the DDRB<3> bit for data direction)

bit 4: **PWM1ON**: PWM1 On bit
1 = PWM1 is enabled (The RB2/PWM1 pin ignores the state of the DDRB<2> bit)
0 = PWM1 is disabled (The RB2/PWM1 pin uses the state of the DDRB<2> bit for data direction)

bit 3: **CA1/$\overline{PR3}$**: CA1/$\overline{PR3}$ Register Mode Select bit
1 = Enables Capture1 (PR3H/CA1H:PR3L/CA1L is the Capture1 register. Timer3 runs without a period register)
0 = Enables the Period register (PR3H/CA1H:PR3L/CA1L is the Period register for Timer3)

bit 2: **TMR3ON**: Timer3 On bit
1 = Starts Timer3
0 = Stops Timer3

bit 1: **TMR2ON**: Timer2 On bit
This bit controls the incrementing of the Timer2 register. When Timer2:Timer1 form the 16-bit timer (T16 is set), TMR2ON must be set. This allows the MSB of the timer to increment.
1 = Starts Timer2 (Must be enabled if the T16 bit (TCON1<3>) is set)
0 = Stops Timer2

bit 0: **TMR1ON**: Timer1 On bit
When T16 is set (in 16-bit Timer Mode)
1 = Starts 16-bit Timer2:Timer1
0 = Stops 16-bit Timer2:Timer1

When T16 is clear (in 8-bit Timer Mode)
1 = Starts 8-bit Timer1
0 = Stops 8-bit Timer1

FIGURE 13-3: USART TRANSMIT

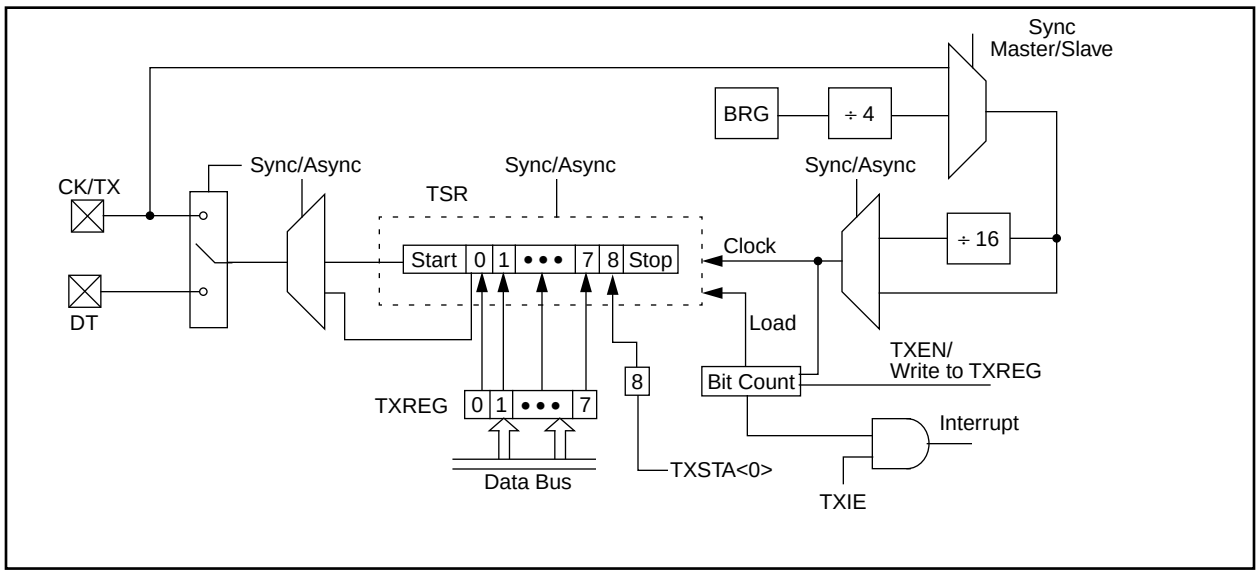
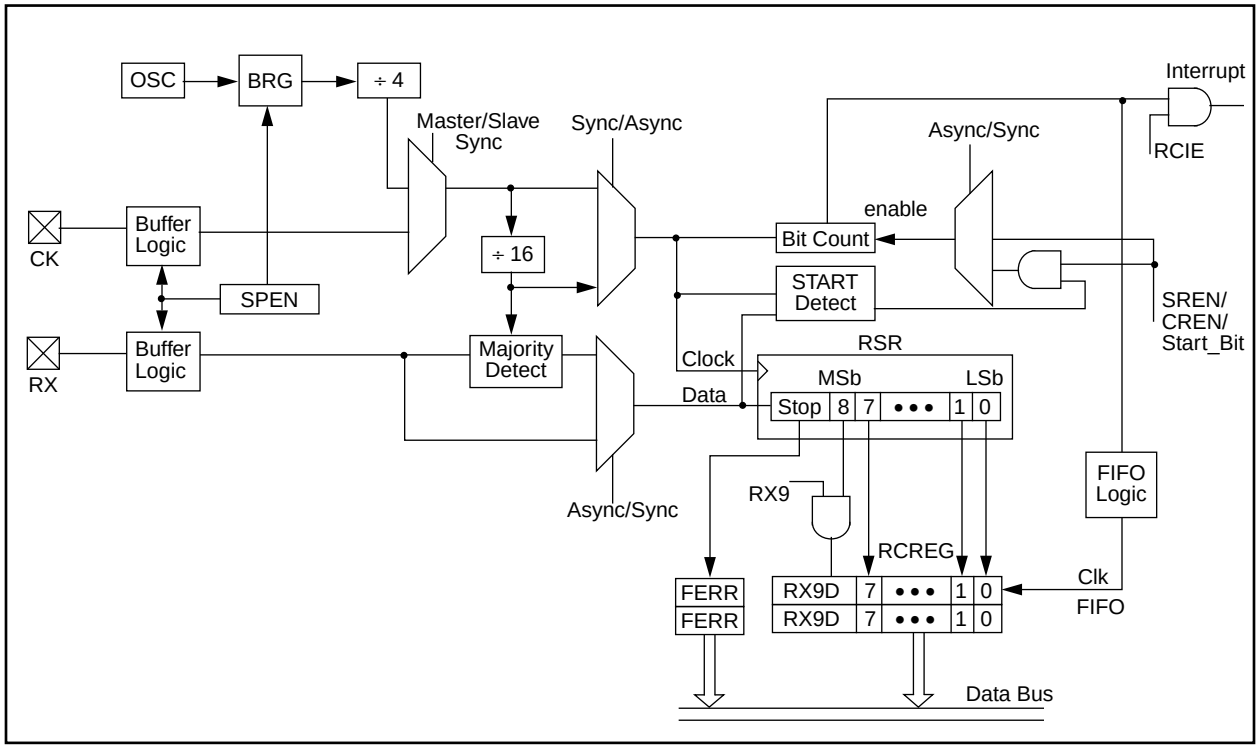


FIGURE 13-4: USART RECEIVE

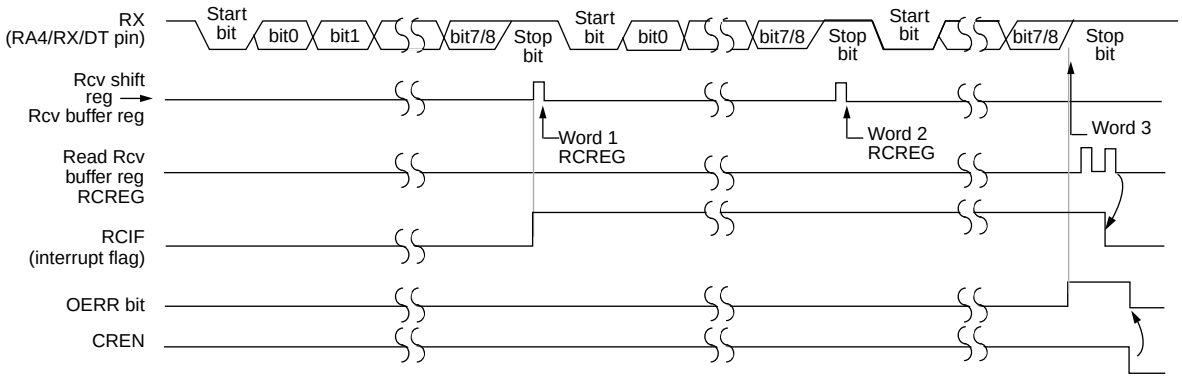


Steps to follow when setting up an Asynchronous Reception:

1. Initialize the SPBRG register for the appropriate baud rate.
2. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
3. If interrupts are desired, then set the RCIE bit.
4. If 9-bit reception is desired, then set the RX9 bit.
5. Enable the reception by setting the CREN bit.
6. The RCIF bit will be set when reception completes and an interrupt will be generated if the RCIE bit was set.
7. Read RCSTA to get the ninth bit (if enabled) and FERR bit to determine if any error occurred during reception.
8. Read RCREG for the 8-bit received data.
9. If an overrun error occurred, clear the error by clearing the OERR bit.

Note: To terminate a reception, either clear the SREN and CREN bits, or the SPEN bit. This will reset the receive logic, so that it will be in the proper state when receive is re-enabled.

FIGURE 13-8: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX input. The RCREG (receive buffer) is read after the third word, causing the OERR (overrun) bit to be set.

TABLE 13-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
16h, Bank 1	PIR	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TXIF	RCIF	0000 0010	0000 0010
13h, Bank 0	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00u
14h, Bank 0	RCREG	RX7	RX6	RX5	RX4	RX3	RX2	RX1	RX0	xxxx xxxx	uuuu uuuu
17h, Bank 1	PIE	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TXIE	RCIE	0000 0000	0000 0000
15h, Bank 0	TXSTA	CSRC	TX9	TXEN	SYNC	—	—	TRMT	TX9D	0000 --1x	0000 --1u
17h, Bank 0	SPBRG	Baud rate generator register								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as a '0', shaded cells are not used for asynchronous reception.
Note 1: Other (non power-up) resets include: external reset through $\overline{\text{MCLR}}$ and Watchdog Timer Reset.

13.3.2 USART SYNCHRONOUS MASTER RECEPTION

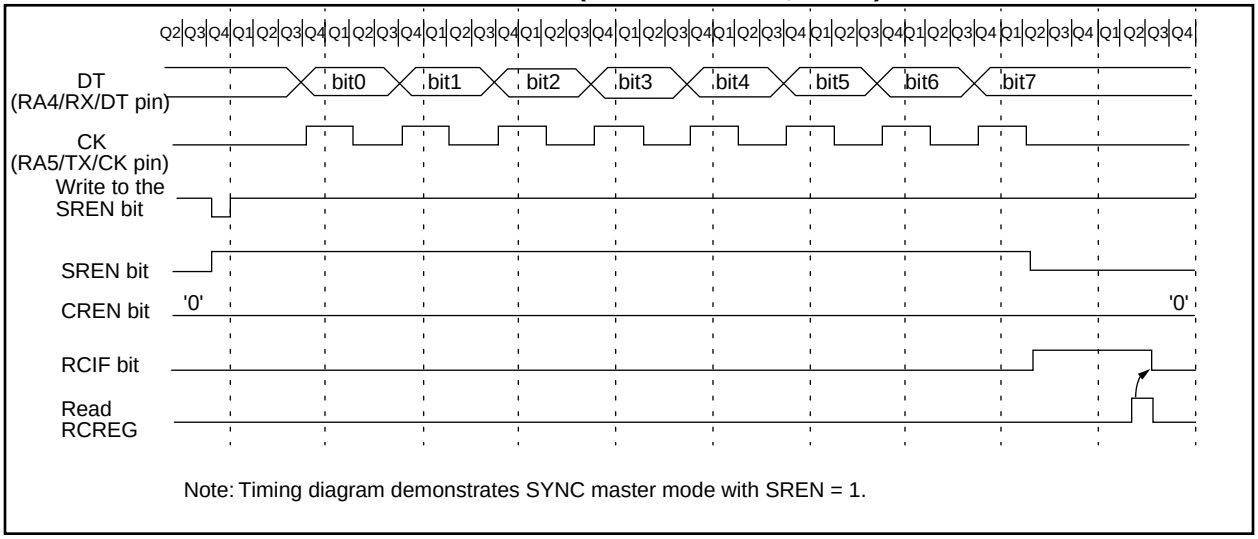
Once synchronous mode is selected, reception is enabled by setting either the SREN (RCSTA<5>) bit or the CREN (RCSTA<4>) bit. Data is sampled on the RA4/RX/DT pin on the falling edge of the clock. If SREN is set, then only a single word is received. If CREN is set, the reception is continuous until CREN is reset. If both bits are set, then CREN takes precedence. After clocking the last bit, the received data in the Receive Shift Register (RSR) is transferred to RCREG (if it is empty). If the transfer is complete, the interrupt bit RCIF (PIR<0>) is set. The actual interrupt can be enabled/disabled by setting/clearing the RCIE (PIE<0>) bit. RCIF is a read only bit which is RESET by the hardware. In this case it is reset when RCREG has been read and is empty. RCREG is a double buffered register; i.e., it is a two deep FIFO. It is possible for two bytes of data to be received and transferred to the RCREG FIFO and a third byte to begin shifting into the RSR. On the clocking of the last bit of the third byte, if RCREG is still full, then the overrun error bit OERR (RCSTA<1>) is set. The word in the RSR will be lost. RCREG can be read twice to retrieve the two bytes in the FIFO. The OERR bit has to be cleared in software. This is done by clearing the CREN bit. If OERR bit is set, transfers from RSR to RCREG are inhibited, so it is essential to clear OERR bit if it is set. The 9th receive bit is buffered the same way as the receive data. Reading the RCREG register will allow the RX9D and FERR bits to be loaded with values for the next received data; therefore, it is essential for the user to read the RCSTA register before reading RCREG in order not to lose the old FERR and RX9D information.

Steps to follow when setting up a Synchronous Master Reception:

1. Initialize the SPBRG register for the appropriate baud rate. See Section 13.1 for details.
2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
3. If interrupts are desired, then set the RCIE bit.
4. If 9-bit reception is desired, then set the RX9 bit.
5. If a single reception is required, set bit SREN. For continuous reception set bit CREN.
6. The RCIF bit will be set when reception is complete and an interrupt will be generated if the RCIE bit was set.
7. Read RCSTA to get the ninth bit (if enabled) and determine if any error occurred during reception.
8. Read the 8-bit received data by reading RCREG.
9. If any error occurred, clear the error by clearing CREN.

Note:	To terminate a reception, either clear the SREN and CREN bits, or the SPEN bit. This will reset the receive logic, so that it will be in the proper state when receive is re-enabled.

FIGURE 13-11: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates SYNC master mode with SREN = 1.

RLNCF **Rotate Left f (no carry)**

Syntax: [*label*] RLNCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

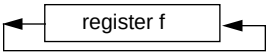
Operation: f<n> → d<n+1>;
f<7> → d<0>

Status Affected: None

Encoding:

0010	001d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the left. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: RLNCF REG, 1

Before Instruction
C = 0
REG = 1110 1011

After Instruction
C =
REG = 1101 0111

RRCF **Rotate Right f through Carry**

Syntax: [*label*] RRCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

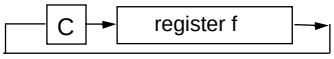
Operation: f<n> → d<n-1>;
f<0> → C;
C → d<7>

Status Affected: C

Encoding:

0001	100d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: RRCF REG1,0

Before Instruction
REG1 = 1110 0110
C = 0

After Instruction
REG1 = 1110 0110
WREG = 0111 0011
C = 0

NOTES:

TABLE 16-1: DEVELOPMENT TOOLS FROM MICROCHIP

Product	** MPLAB™ Integrated Development Environment	MPLAB™ C Compiler	MP-DriveWay Applications Code Generator	fuzzyTECH®-MP Explorer/Edition Fuzzy Logic Dev. Tool	*** PICMASTER® PICMASTER-CE In-Circuit Emulator	ICEPIC Low-Cost In-Circuit Emulator	****PRO MATE™ II Universal Microchip Programmer	PICSTART® Lite Ultra Low-Cost Dev. Kit	PICSTART® Plus Low-Cost Universal Dev. Kit
PIC12C508, 509	SW007002	SW006005	—	—	EM167015/ EM167101	—	DV007003	—	DV003001
PIC14000	SW007002	SW006005	—	—	EM147001/ EM147101	—	DV007003	—	DV003001
PIC16C52, 54, 54A, 55, 56, 57, 58A	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167015/ EM167101	EM167201	DV007003	DV162003	DV003001
PIC16C554, 556, 558	SW007002	SW006005	—	DV005001/ DV005002	EM167033/ EM167113	—-	DV007003	—	DV003001
PIC16C61	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167021/ N/A	EM167205	DV007003	DV162003	DV003001
PIC16C62, 62A, 64, 64A	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167025/ EM167103	EM167203	DV007003	DV162002	DV003001
PIC16C620, 621, 622	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167023/ EM167109	EM167202	DV007003	DV162003	DV003001
PIC16C63, 65, 65A, 73, 73A, 74, 74A	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167025/ EM167103	EM167204	DV007003	DV162002	DV003001
PIC16C642, 662*	SW007002	SW006005	—	—	EM167035/ EM167105	—-	DV007003	DV162002	DV003001
PIC16C71	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167027/ EM167105	EM167205	DV007003	DV162003	DV003001
PIC16C710, 711	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167027/ EM167105	—	DV007003	DV162003	DV003001
PIC16C72	SW007002	SW006005	SW006006	—	EM167025/ EM167103	—	DV007003	DV162002	DV003001
PIC16F83	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167029/ EM167107	—	DV007003	DV162003	DV003001
PIC16C84	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167029/ EM167107	EM167206	DV007003	DV162003	DV003001
PIC16F84	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167029/ EM167107	—	DV007003	DV162003	DV003001
PIC16C923, 924*	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167031/ EM167111	—	DV007003	—	DV003001
PIC17C42, 42A, 43, 44	SW007002	SW006005	SW006006	DV005001/ DV005002	EM177007/ EM177107	—	DV007003	—	DV003001

*Contact Microchip Technology for availability date
**MPLAB Integrated Development Environment includes MPLAB-SIM Simulator and MPASM Assembler

***All PICMASTER and PICMASTER-CE ordering part numbers above include PRO MATE II programmer
****PRO MATE socket modules are ordered separately. See development systems ordering guide for specific ordering part numbers

Product	TRUEGAUGE® Development Kit	SEEVAL® Designers Kit	Hopping Code Security Programmer Kit	Hopping Code Security Eval/Demo Kit
All 2 wire and 3 wire Serial EEPROM's	N/A	DV243001	N/A	N/A
MTA11200B	DV114001	N/A	N/A	N/A
HCS200, 300, 301 *	N/A	N/A	PG306001	DM303001

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

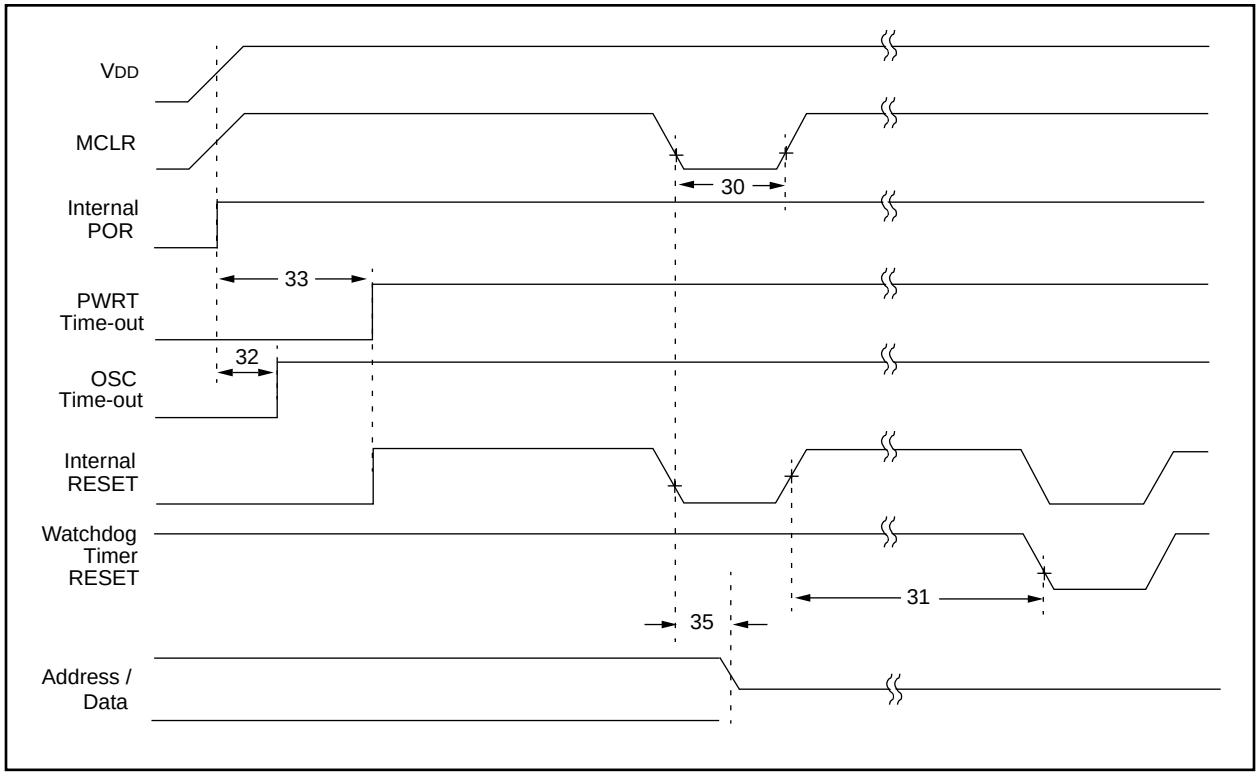


TABLE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	100 *	—	—	ns	
31	Twdt	Watchdog Timer Time-out Period (Prescale = 1)	5 *	12	25 *	ms	
32	Tost	Oscillation Start-up Timer Period		1024 TOSC §		ms	TOSC = OSC1 period
33	Tpwrt	Power-up Timer Period	40 *	96	200 *	ms	
35	TmcL2adl	$\overline{\text{MCLR}}$ to System Interface bus (AD15:AD0) invalid	—	—	100 *	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

§ This specification ensured by design.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-5: TRANSCONDUCTANCE (gm) OF LF OSCILLATOR vs. VDD

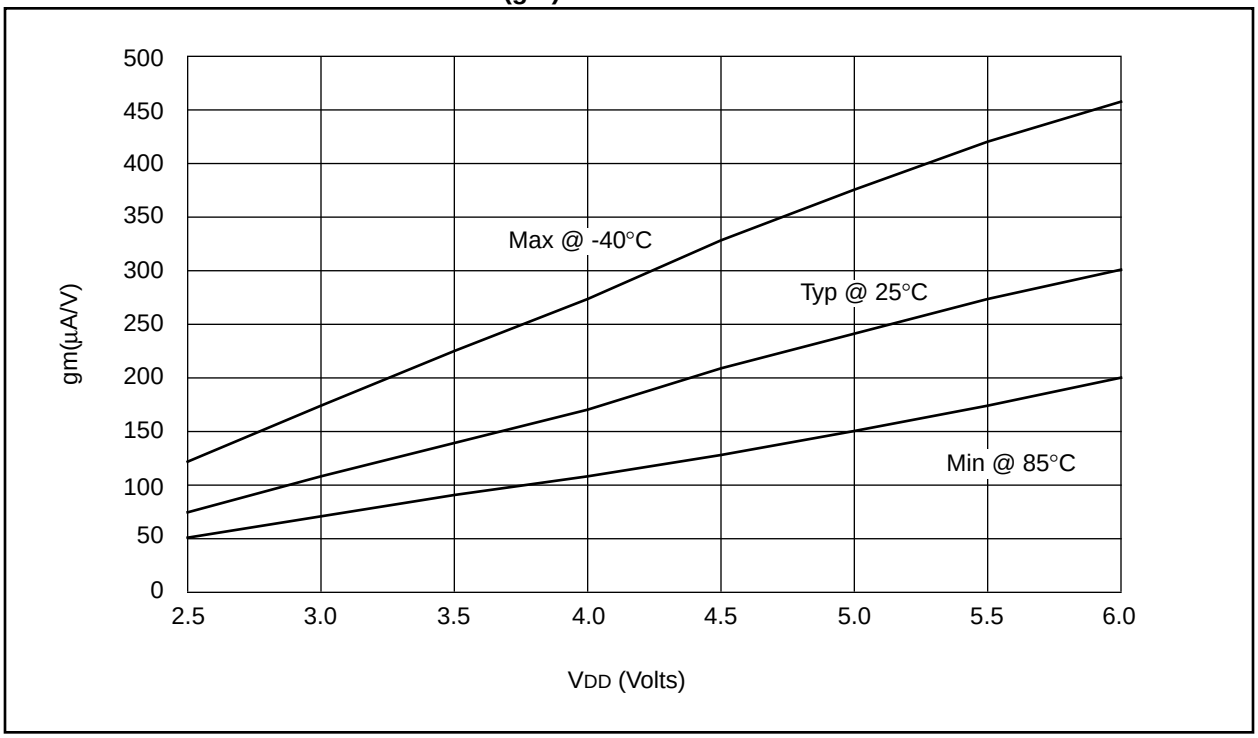
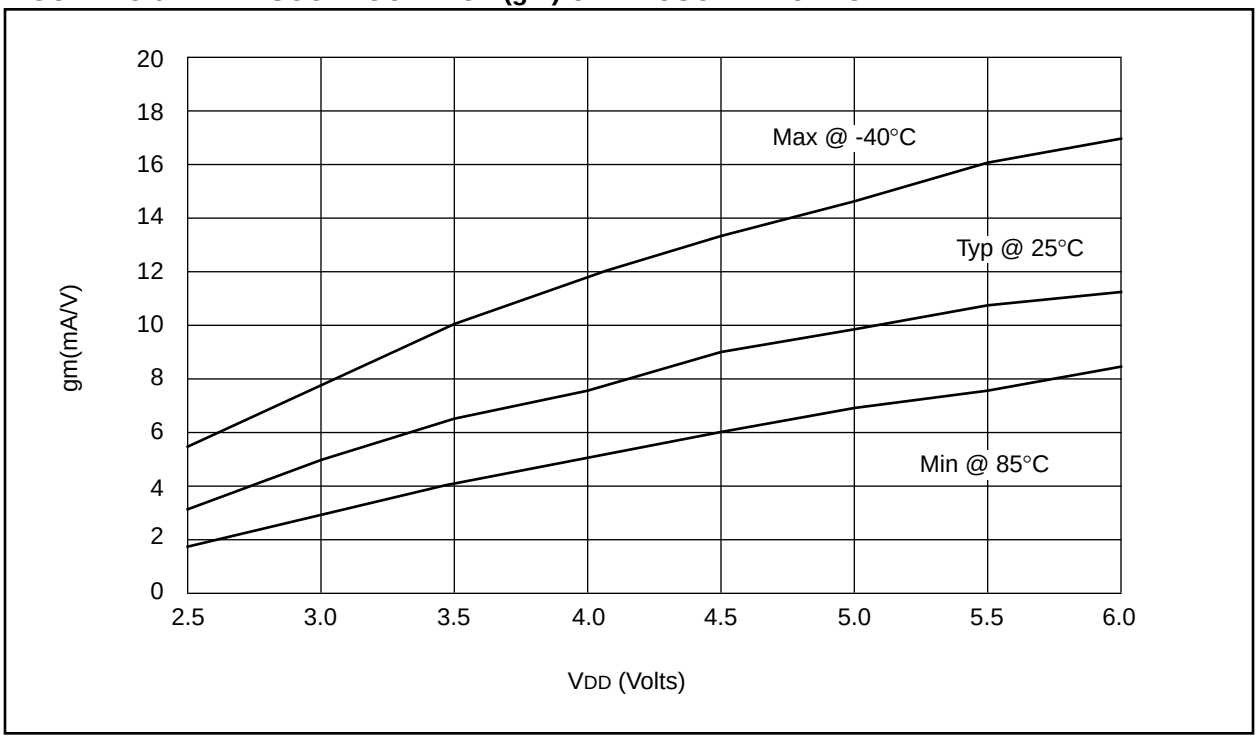


FIGURE 18-6: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-19: V_{TH}, V_{IL} of I/O PINS (SCHMITT TRIGGER) vs. V_{DD}

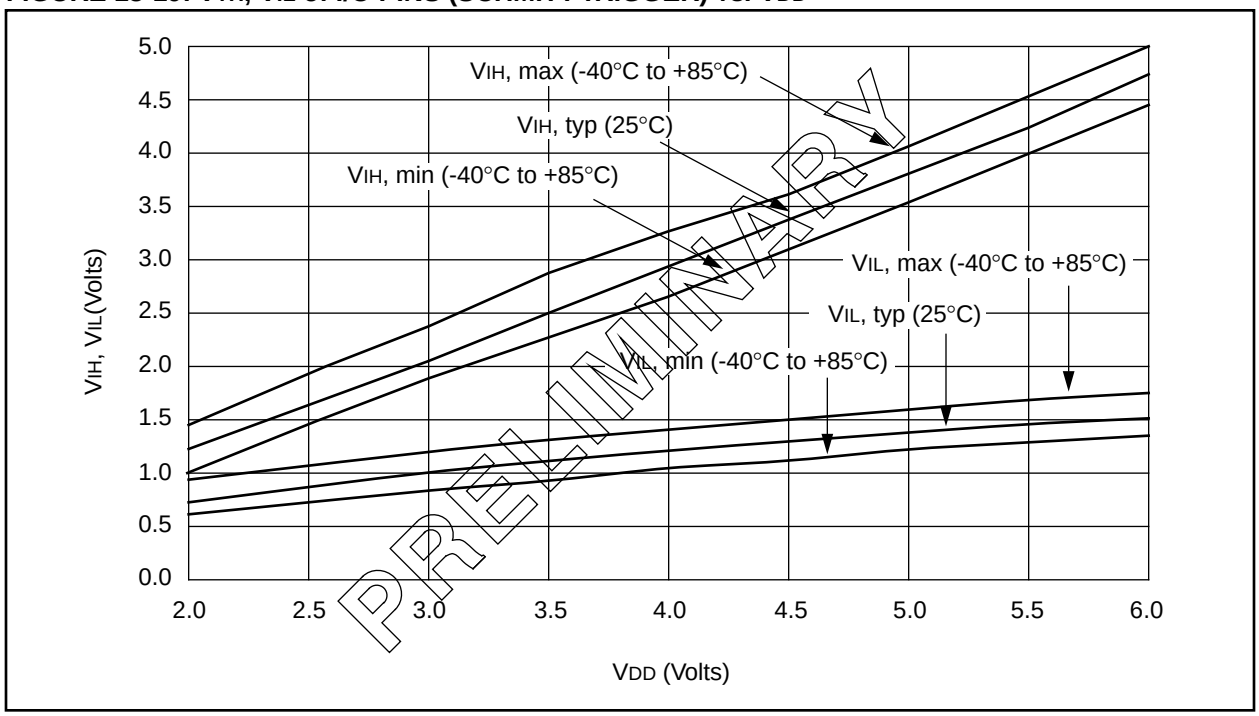
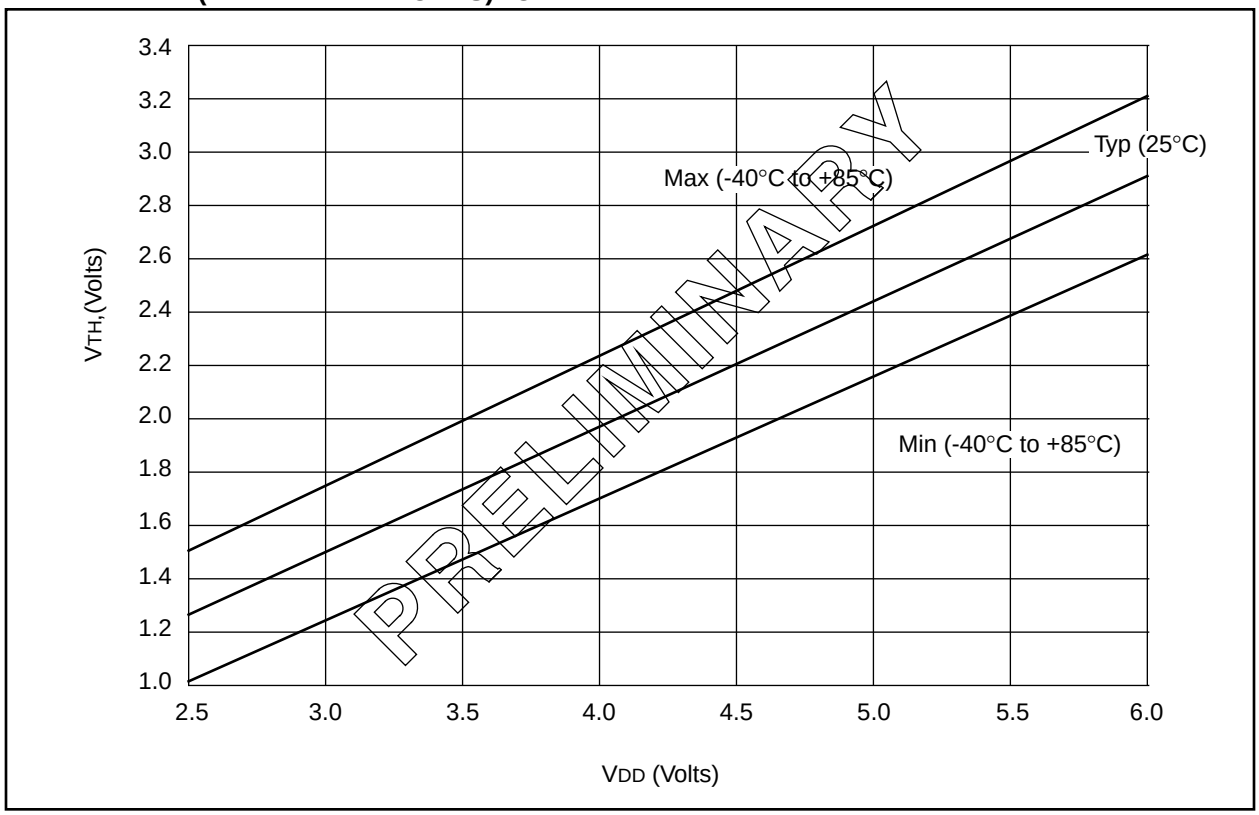


FIGURE 18-20: V_{TH} (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (IN XT AND LF MODES) vs. V_{DD}



Applicable Devices	42	R42	42A	43	R43	44

19.0 PIC17CR42/42A/43/R43/44 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125˚C

Storage temperature ..... -65˚C to +150˚C

Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) ..... -0.6V to +14V

Voltage on RA2 and RA3 with respect to V_{SS} ..... -0.6V to +14V

Voltage on all other pins with respect to V_{SS} ..... -0.6V to V_{DD} + 0.6V

Total power dissipation (Note 1) 1.0W

Maximum current out of V_{SS} pin(s) - total ..... 250 mA

Maximum current into V_{DD} pin(s) - total ..... 200 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA

Maximum output current sunk by any I/O pin (except RA2 and RA3) ..... 35 mA

Maximum output current sunk by RA2 or RA3 pins ..... 60 mA

Maximum output current sourced by any I/O pin ..... 20 mA

Maximum current sunk by PORTA and PORTB (combined) ..... 150 mA

Maximum current sourced by PORTA and PORTB (combined) ..... 100 mA

Maximum current sunk by PORTC, PORTD and PORTE (combined) ..... 150 mA

Maximum current sourced by PORTC, PORTD and PORTE (combined) ..... 100 mA

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Applicable Devices	42	R42	42A	43	R43	44

DC CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)
Operating temperature
-40°C ≤ TA ≤ +85°C for industrial and
0°C ≤ TA ≤ +70°C for commercial
Operating voltage VDD range as described in Section 19.1

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
		Output Low Voltage					
D080	VOL	I/O ports (except RA2 and RA3)					IOL = VDD/1.250 mA
			–	–	0.1VDD	V	4.5V ≤ VDD ≤ 6.0V
			–	–	0.1VDD *	V	VDD = 2.5V
D081		with TTL buffer	–	–	0.4	V	IOL = 6 mA, VDD = 4.5V Note 6
D082		RA2 and RA3	–	–	3.0	V	IOL = 60.0 mA, VDD = 6.0V
D083		OSC2/CLKOUT	–	–	0.4	V	IOL = 1 mA, VDD = 4.5V
D084		(RC and EC osc modes)	–	–	0.1VDD *	V	IOL = VDD/5 mA (PIC17LC43/LC44 only)
		Output High Voltage (Note 3)					
D090	VOH	I/O ports (except RA2 and RA3)					IOH = -VDD/2.500 mA
			0.9VDD	–	–	V	4.5V ≤ VDD ≤ 6.0V
			0.9VDD *	–	–	V	VDD = 2.5V
D091		with TTL buffer	2.4	–	–	V	IOH = -6.0 mA, VDD=4.5V Note 6
D092		RA2 and RA3	–	–	12	V	Pulled-up to externally applied voltage
D093		OSC2/CLKOUT	2.4	–	–	V	IOH = -5 mA, VDD = 4.5V
D094		(RC and EC osc modes)	0.9VDD *	–	–	V	IOH = -VDD/5 mA (PIC17LC43/LC44 only)
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2/CLKOUT pin	–	–	25	pF	In EC or RC osc modes when OSC2 pin is outputting CLKOUT. external clock is used to drive OSC1.
D101	CIO	All I/O pins and OSC2 (in RC mode)	–	–	50	pF	
D102	CAD	System Interface Bus (PORTC, PORTD and PORTE)	–	–	50	pF	In Microprocessor or Extended Microcontroller mode

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC17CXX devices be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17CXX Programming Specifications (Literature number DS30139).

5: The $\overline{MCLR}$/VPP pin may be kept in this range at times other than programming, but is not recommended.

6: For TTL buffers, the better of the two specifications may be used.

Applicable Devices	42	R42	42A	43	R43	44

19.5 Timing Diagrams and Specifications

FIGURE 19-2: EXTERNAL CLOCK TIMING

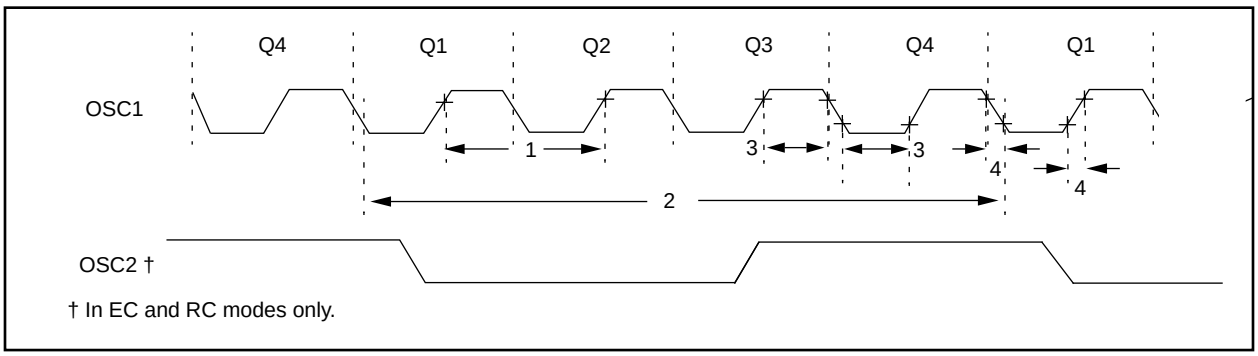


TABLE 19-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency (Note 1)**	DC	—	8	MHz	EC osc mode - 08 devices (8 MHz devices)
			DC	—	16	MHz	- 16 devices (16 MHz devices)
			DC	—	25	MHz	- 25 devices (25 MHz devices)
			DC	—	33	MHz	- 33 devices (33 MHz devices)
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			1	—	8	MHz	XT osc mode - 08 devices (8 MHz devices)
			1	—	16	MHz	- 16 devices (16 MHz devices)
			1	—	25	MHz	- 25 devices (25 MHz devices)
			1	—	33	MHz	- 33 devices (33 MHz devices)
			DC	—	2	MHz	LF osc mode
1	Tosc	**External CLKIN Period (Note 1)**	125	—	—	ns	EC osc mode - 08 devices (8 MHz devices)
			62.5	—	—	ns	- 16 devices (16 MHz devices)
			40	—	—	ns	- 25 devices (25 MHz devices)
			30.3	—	—	ns	- 33 devices (33 MHz devices)
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			125	—	1,000	ns	XT osc mode - 08 devices (8 MHz devices)
			62.5	—	1,000	ns	- 16 devices (16 MHz devices)
			40	—	1,000	ns	- 25 devices (25 MHz devices)
			30.3	—	1,000	ns	- 33 devices (33 MHz devices)
			500	—	—	ns	LF osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	121.2	4/Fosc	DC	ns	
3	TosL, TosH	**Clock in (OSC1) high or low time**	10 ‡	—	—	ns	EC oscillator
4	TosR, TosF	**Clock in (OSC1) rise or fall time**	—	—	5 ‡	ns	EC oscillator

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "max." cycle time limit is "DC" (no clock) for all devices.

E.2 PIC16C5X Family of Devices

	Clock	Memory				Peripherals		Features	
	Maximum Frequency of Operation (MHz)	Program Memory (x12 words)	EPROM	ROM	RAM Data Memory (bytes)	Timer Module(s)	I/O Pins	Voltage Range (Volts)	Number of Instructions	Packages
PIC16C52	4	384	—	25	TMR0	12	2.5-6.25	33	18-pin DIP, SOIC
PIC16C54	20	512	—	25	TMR0	12	2.5-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16C54A	20	512	—	25	TMR0	12	2.0-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16CR54A	20	—	512	25	TMR0	12	2.0-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16C55	20	512	—	24	TMR0	20	2.5-6.25	33	28-pin DIP, SOIC, SSOP
PIC16C56	20	1K	—	25	TMR0	12	2.5-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16C57	20	2K	—	72	TMR0	20	2.5-6.25	33	28-pin DIP, SOIC, SSOP
PIC16CR57B	20	—	2K	72	TMR0	20	2.5-6.25	33	28-pin DIP, SOIC, SSOP
PIC16C58A	20	2K	—	73	TMR0	12	2.0-6.25	33	18-pin DIP, SOIC; 20-pin SSOP
PIC16CR58A	20	—	2K	73	TMR0	12	2.5-6.25	33	18-pin DIP, SOIC; 20-pin SSOP

All PIC16/17 Family devices have Power-On Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.

APPENDIX F: ERRATA FOR PIC17C42 SILICON

The PIC17C42 devices that you have received have the following anomalies. At present there is no intention for future revisions to the present PIC17C42 silicon. If these cause issues for the application, it is recommended that you select the PIC17C42A device.

Note:	New designs should use the PIC17C42A.

1. When the Oscillator Start-Up Timer (OST) is enabled (in LF or XT oscillator modes), any interrupt that wakes the processor may cause a WDT reset. This occurs when the WDT is greater than or equal to 50% time-out period when the SLEEP instruction is executed. This will not occur in either the EC or RC oscillator modes.

   Work-arounds

a) Always ensure that the CLRWDT instruction is executed before the WDT increments past 50% of the WDT period. This will keep the “false” WDT reset from occurring.
b) When using the WDT as a normal timer (WDT disabled), ensure that the WDT is less than or equal to 50% time-out period when the SLEEP instruction is executed. This can be done by monitoring the $\overline{TO}$ bit for changing state from set to clear. Example 1 shows putting the PIC17C42 to sleep.

EXAMPLE F-1: PIC17C42 TO SLEEP

```
      BTFSS   CPUSTA, TO  ; TO = 0?
      CLRWDT              ; YES, WDT = 0
LOOP  BTFSC   CPUSTA, TO  ; WDT rollover?
      GOTO    LOOP        ; NO, Wait
      SLEEP               ; YES, goto Sleep
```

2. When the clock source of Timer1 or Timer2 is selected to external clock, the overflow interrupt flag will be set twice, once when the timer equals the period, and again when the timer value is reset to 0h. If the latency to clear TMRxIF is greater than the time to the next clock pulse, no problems will be noticed. If the latency is less than the time to the next timer clock pulse, the interrupt will be serviced twice.

   Work-arounds

a) Ensure that the timer has rolled over to 0h before clearing the flag bit.
b) Clear the timer in software. Clearing the timer in software causes the period to be one count less than expected.

Design considerations

The device must not be operated outside of the specified voltage range. An external reset circuit must be used to ensure the device is in reset when a brown-out occurs or the V_{DD} rise time is too long. Failure to ensure that the device is in reset when device voltage is out of specification may cause the device to lock-up and ignore the $\overline{MCLR}$ pin.

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